SN74ALVC16409 9-BIT, 4-PORT UNIVERSAL BUS EXCHANGER WITH 3-STATE OUTPUTS

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33**∏** 2B8

32 ∏ GND

31 1 2B9

30 SEL4

29 **∏** SEL3

2A8 | 24 GND ∏25

2A9 ∏ 26 SEL1 [] 27

SEL2

28

DGG OR DL PACKAGE EPIC ™ (Enhanced-Performance Implanted (TOP VIEW) **CMOS) Submicron Process Member of the Texas Instruments** 56 CLK PRE Widebus+™ Family SEL0 12 55 SELEN UBE™ (Universal Bus Exchanger) Allows 1A1 🛮 3 54 1B1 Synchronous Data Exchange 53 GND GND 4 Designed to Facilitate Incident-Wave 52 1B2 1A2 5 Switching for Line Impedances of 50 Ω 51 1B3 1A3 6 or Greater 50 VCC V_{CC} L 7 Typical V_{OLP} (Output Ground Bounce) 49**∏** 1B4 1A4 8 $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$ 1A5 | 9 48**∏** 1B5 47 1B6 1A6 🛮 10 Typical V_{OHV} (Output V_{OH} Undershoot) GND [46 ∏ GND > 2 V at V_{CC} = 3.3 V, T_A = 25°C 11 1A7 🛮 12 45 1B7 ESD Protection Exceeds 2000 V Per 1A8 44**∏** 1B8 13 MIL-STD-883C. Method 3015: Exceeds 43 1 1B9 1А9 П 14 200 V Using Machine Model 42 2B1 2A1 15 (C = 200 pF, R = 0)2A2 **1**16 41 **∏** 2B2 Bus Hold on Data Inputs Eliminates the 40**∏** 2B3 2A3 17 **Need for External Pullup/Pulldown** GND 18 39 **∏** GND 2A4 🛮 38**∏** 2B4 19 Latch-Up Performance Exceeds 250 mA 37 1 2B5 2A5 🛭 20 Per JEDEC Standard JESD-17 2A6 21 36**∏** 2B6 Package Options Include Plastic 300-mil. V_{CC} 422 35 V_{CC} Shrink Small-Outline (DL) and Thin Shrink 2A7 🛮 23 34**∏** 2B7

description

The SN74ALVC16409 allows synchronous data exchange between four different buses.

Small-Outline (DGG) Packages

Data flow is controlled by the select (SEL0-SEL4) inputs. A data-flow state is stored on the rising edge of the clock (CLK) input if the select-enable (SELEN) input is low. Once a data-flow state has been established, data is stored in the flip-flop on the rising edge of CLK if SELEN is high.

The data-flow control logic is designed to allow glitch-free data transmission.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVC16409 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN74ALVC16409 is characterized for operation from −40°C to 85°C.

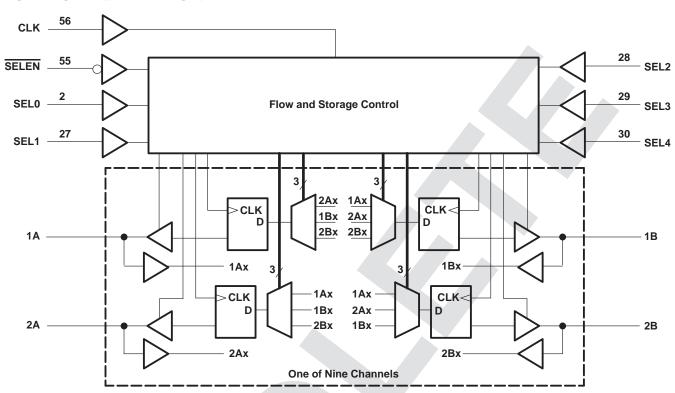


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logic diagram (positive logic)



FUNCTION TABLE

INF	PUTS	OUTPUT				
CLK	SEND PORT	RECEIVE PORT				
Х	X	в ₀ †				
X	L	L				
X	Н	Н				
\uparrow	L	L				
1	Н	Н				
Н	Χ	_{В0} † _{В0} †				
L	Х	в ₀ †				

† Output level before the indicated steady-state input conditions were established



DATA-FLOW CONTROL FUNCTION TABLE

	INPUTS						5.454 51 61W
SELEN	CLK	SEL0	SEL1	SEL2	SEL3	SEL4	DATA FLOW
Н	1	Х	Х	Х	Χ	Χ	No change
L	\uparrow	0	0	0	0	0	None, all I/Os off
L	\uparrow	0	0	0	0	1	Not used
L	\uparrow	0	0	0	1	0	Not used
L	\uparrow	0	0	0	1	1	Not used
L	\uparrow	0	0	1	0	0	Not used
L	\uparrow	0	0	1	0	1	Not used
L	\uparrow	0	0	1	1	0	Not used
L	\uparrow	0	0	1	1	1	Not used
L	\uparrow	0	1	0	0	0	2A to 1A and 1B to 2B
L	\uparrow	0	1	0	0	1	2A to 1A
L	\uparrow	0	1	0	1	0	2B to 1B
L	\uparrow	0	1	0	1	1	2A to 1A and 2B to 1B
L	\uparrow	0	1	1	0	0	1A to 2A and 1B to 2B
L	\uparrow	0	1	1	0	1	1A to 2A
L	\uparrow	0	1	1	1	0	1B to 2B
L	\uparrow	0	1	1	1	1	1A to 2A and 2B to 1B
L	\uparrow	1	0	0	0	0	1A to 1B and 2B to 2A
L	\uparrow	1	0	0	0	1	1A to 1B
L	\uparrow	1	0	0	1	0	2A to 2B
L	\uparrow	1	0	0	1	1	1A to 1B and 2A to 2B
L	\uparrow	1	0	1	0	0	1B to 1A and 2A to 2B
L	\uparrow	1	0	1	0	1	1B to 1A
L	\uparrow	1	0	1	1	0	2B to 2A
L	1	1	0	1	1	1	1B to 1A and 2B to 2A
L	1	1	1	0	0	0	2B to 1A and 2A to 1B
L	\uparrow	1	1	0	0	1	1B to 2A
L	1	1	1	0	1	0	2B to 1A
L	1	1	1	0	1	1	2B to 1A and 1B to 2A
L	1	1	1	1	0	0	1A to 2B and 1B to 2A
L	1	1	1	1	0	1	1A to 2B
L	\uparrow	1	1	1	1	0	2A to 1B
L	1	1	1	1	1	1	1A to 2B and 2A to 1B



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} –0.5 V to 4.6 V
Input voltage range, VI: Except I/O ports (see Note 1)
I/O ports (see Notes 1 and 2)
Output voltage range, V _O (see Notes 1 and 2)
Input clamp current, $I_{ K }(V_1 < 0)$ -50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) ± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) ± 50 mA
Continuous current through V _{CC} or GND pins ±100 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DGG package
DL package 1.4 W
Storage temperature range, T _{stg} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2.7	3.6	V	
V	High-level input voltage		2		V	
V _{IH} F	Tilgir-level lilput voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
V _{IL}	Low level input veltage	V _{CC} = 2.7 V to 3.6 V		0.8	V	
	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
VI	Input voltage		0	VCC	V	
VO	Output voltage		0	VCC	V	
		V _{CC} = 2.3 V		-12		
lOH	High-level output current	V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 2.3 V		12		
lOL	Low-level output current V _{CC} = 2.7 V			12	mA	
		V _{CC} = 3 V				
Δt/Δν	Input transition rise or fall rate		0	10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST	v _{cc} †	T _A = -	-40°C to	85°C	UNIT		
PARAMETER	1531	TEST CONDITIONS			TYP‡	MAX	ONIT	
	I _{OH} = -100 μA	MIN to MAX	V _{CC} -0	.2				
	$I_{OH} = -6 \text{ mA}$	V _{IH} = 1.7 V	2.3 V	2				
Vari		V _{IH} = 1.7 V	2.3 V	1.7			V	
VOH	$I_{OH} = -12 \text{ mA}$	V _{IH} = 2 V	2.7 V	2.2			V	
		V _{IH} = 2 V	3 V	2.4				
	$I_{OH} = -24 \text{ mA}$	V _{IH} = 2 V	3 V	2				
	I _{OL} = 100 μA		MIN to MAX			0.2	<u> </u>	
	$I_{OL} = 6 \text{ mA}$	V _{IL} = 0.7 V	2.3 V			0.4		
VOL	lo. – 12 mA	V _{IL} = 0.7 V	2.3 V			0.7		
	I _{OL} = 12 mA	V _{IL} = 0.8 V	2.7 V		0.4			
	I _{OL} = 24 mA	V _{IL} = 0.8 V	3 V			0.55		
ΙĮ	$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
	V _I = 0.7 V		2.3 V	45				
	V _I = 1.7 V		2.3 V	-45				
I _{I(hold)}	$V_{I} = 0.8 \text{ V}$ $V_{I} = 2 \text{ V}$		3 V	75			μΑ	
			3 4	-75				
	V _I = 0 to 3.6 V		3.6 V			±500		
loz§	$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
Icc	$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
∆lcc	One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			500	μΑ	
Ci	$V_I = V_{CC}$ or GND		3.3 V		4		pF	
Co	$V_O = V_{CC}$ or GND		3.3 V		8		pF	

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} =		V _{CC} = 2.7 V	V _{CC} =		UNIT	
			MIN	MAX	MIN	MIN	MAX		
fclock	Clock frequency		0	120		0	120	MHz	
t _W	Pulse duration, CLK high or low		4.2		4.2	3		ns	
	Setup time	A or B before CLK↑	1.9		1.9	1.4			
 .		S before CLK↑	5.1		4.2	3.5		ns	
t _{su}		SELEN before CLK↑	2.5		2.5	1.8			
		PRE before CLK↑	1		1	0.7			
		A or B after CLK↑	0.8		0.8	1			
th	Hold time	S after CLK↑	0		0	0		ns	
		SELEN after CLK↑	0.5		0.5	0.8			



 $[\]ddagger$ All typical values are measured at V_{CC} = 3.3 V, T_A = 25°C. § For I/O ports, the parameter I_{OZ} includes the input leakage current.

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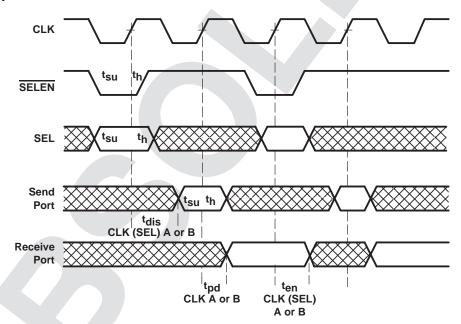
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷c	C = 2.5 ± 0.2 V	V	V _{CC} = 2.7 V	٧٥	± 0.3 V	V	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MAX	MIN	TYP	MAX	
f _{max}			120				120			MHz
t _{pd}	CLK (A or B)	B or A	2	4.2	6.6	5.7	1.5	3.3	5.1	ns
t _{en}	CLK (SEL)	A or B	2.5	4.8	7.4	6.3	2	3.8	5.7	ns
t _{dis}	CLK (SEL)	A or B	3	5.1	7.3	6	2	4	5.7	ns
t _{dis}	PRE	A or B	3.5	5.5	7.7	6.5	2.5	4.2	6.1	ns

operating characteristics, $T_A = 25^{\circ}C$

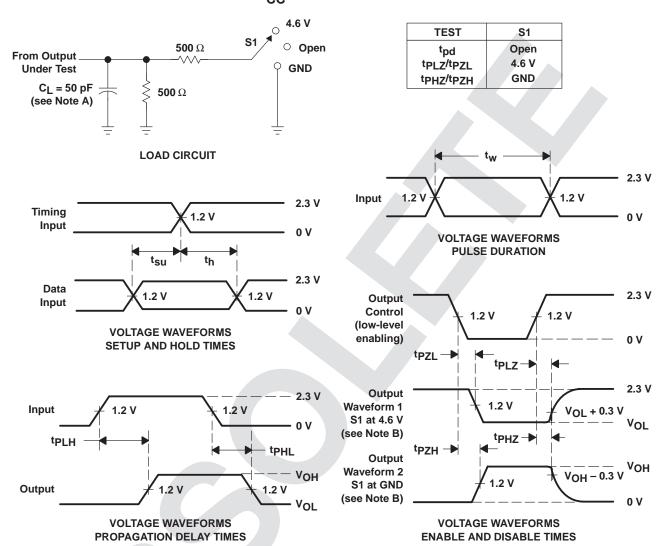
PARAMETER			TEST CONDITIONS	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT
				TYP	TYP	
C _{pd} Power dissipation capacitance		Outputs enabled	C ₁ = 50 pF. f = 10 MHz	60	60	pF
		Outputs disabled	$C_L = 50 \text{ pF}, \qquad f = 10 \text{ MHz}$	00	00	Pr

timing diagram





PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V

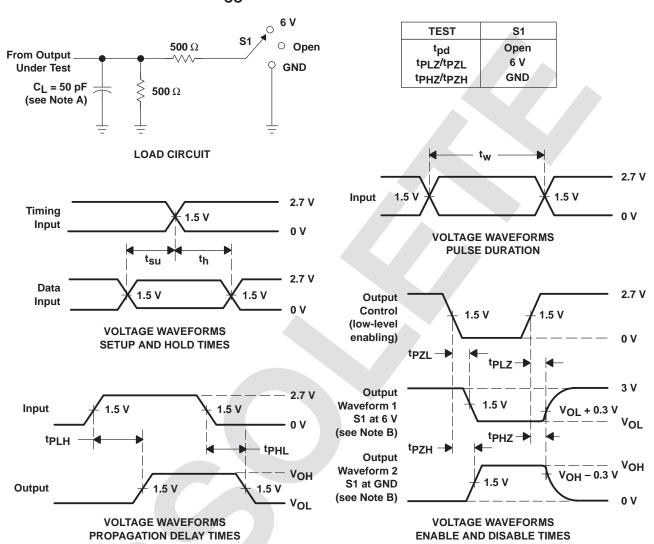


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5 \text{ ns.}$ $t_f \leq 2.5 \text{ ns.}$
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



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